



EV085425502

EC
2-13-03
35/I

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-981~
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO NOVEMBER 5, 2002 EX PARTE QUAYLE OFFICE ACTION

To: Box Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

From: D. Brent Kenady
Tel. 509-624-4276; Fax 509-838-3424
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

Responsive to the Office Action dated November 5, 2002, Applicant amends and remarks as follows:

AMENDMENTS

In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 CFR § 1.121(c)(1)(i). Cancel all previous versions of any pending claim.

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